

# MMBD4448W

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# MMBD4448W

## 200mW Surface Mount Switching Diode-100V

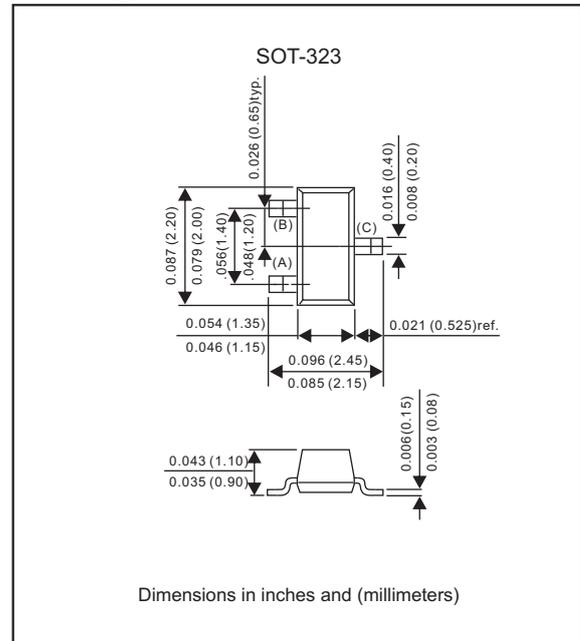
### Features

- Fast switching speed.
- Electrically identical to standard JEDEC.
- Surface mount package ideally suited for automatic insertion.
- Tiny plastic SMD package.
- High conductance.
- Silicon epitaxial planar chip.
- Lead-free parts for green partner, exceeds environmental standards of MIL-STD-19500 /228
- Suffix "-H" indicates Halogen-free part, ex.MMBD4448W-H.

### Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, SOT-323
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Mounting Position : Any
- Weight : Approximated 0.006 gram

### Package Outline



### Maximum ratings (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

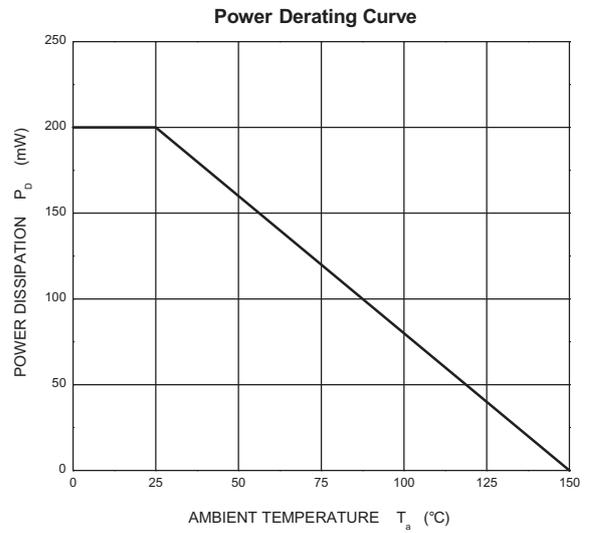
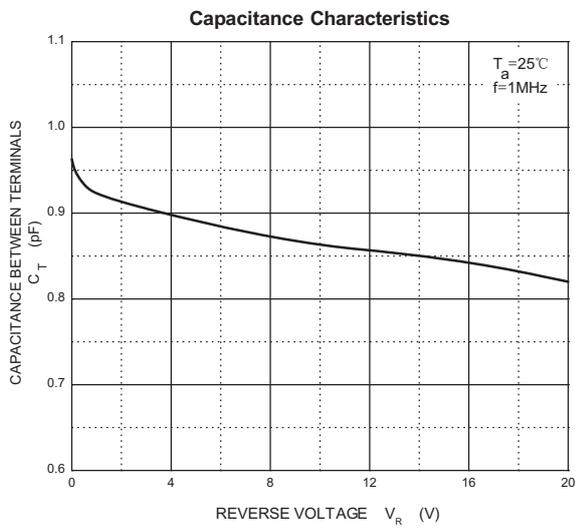
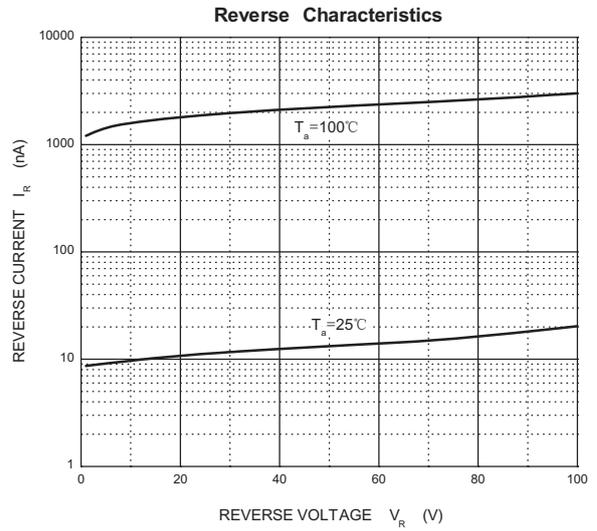
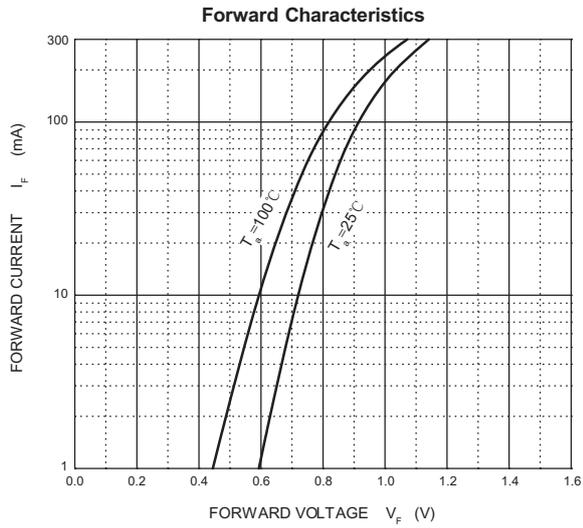
PARAMETER	SYMBOL	LIMIT	UNIT
Non-repetitive peak reverse voltage	$V_{RM}$	100	V
Peak repetitive reverse voltage Working peak reverse voltage DC blocking voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	75	V
RMS reverse voltage	$V_{R(RMS)}$	53	V
Forward continuous current	$I_{FM}$	500	mA
Average rectified output current	$I_O$	250	mA
Non-repetitive peak forward surge current @ $t = 8.3\text{ms}$	$I_{FSM}$	2.0	A
Total device dissipation, note 1	$P_D$	200	mW
Typical thermal resistance junction to ambient	$R_{\theta JA}$	625	$^\circ\text{C/W}$
Operating junction temperature range	$T_J$	-55 to +150	$^\circ\text{C}$
Storage temperature range	$T_{STG}$	-55 to +150	$^\circ\text{C}$

### Electrical characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	TEST CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F=5\text{mA}$	$V_F$	0.62		0.72	V
	$I_F=10\text{mA}$			0.855		
	$I_F=100\text{mA}$			1.0		
	$I_F=150\text{mA}$			1.25		
Reverse leakage current	$V_R=75\text{V}$	$I_R$			2.5	$\mu\text{A}$
	$V_R=20\text{V}$				25	nA
Capacitance between terminals	$V_R = 0\text{V}$ , $f = 1.0\text{MHz}$	$C_T$			4.0	pF
Reverse recovery time	$I_F = I_R = 10\text{mA}$ , $I_{rr} = 0.1 \times I_R$ , $R_L = 100\Omega$	$t_{rr}$			4.0	ns

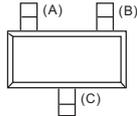
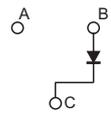
Note 1: Parts Mounted on FR-4 PC Board with recommended pad layout.

## Rating and characteristic curves (MMBD4448W)



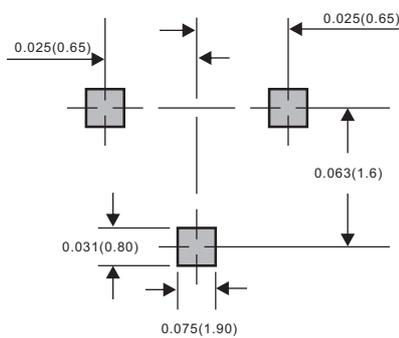
# MMBD4448W

## Pinning information

Type number	Marking code	Simplified outline	Symbol
MMBD4448W	KA3		

## Suggested solder pad layout

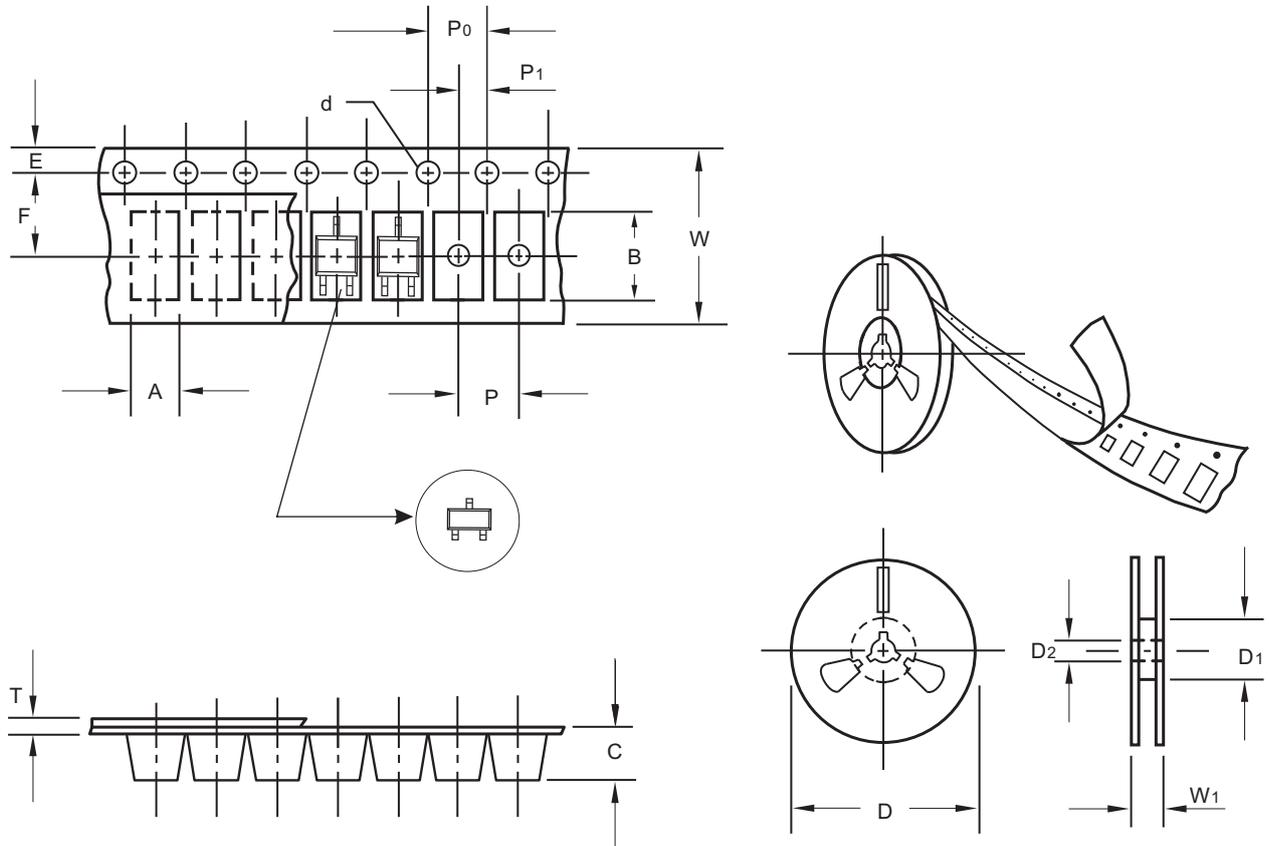
SOT-323



Dimensions in inches and (millimeters)

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## Packing information



unit:mm

Item	Symbol	Tolerance	SOT-323
Carrier width	A	0.1	2.25
Carrier length	B	0.1	2.55
Carrier depth	C	0.1	1.19
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	54.40
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W1	1.0	11.40

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

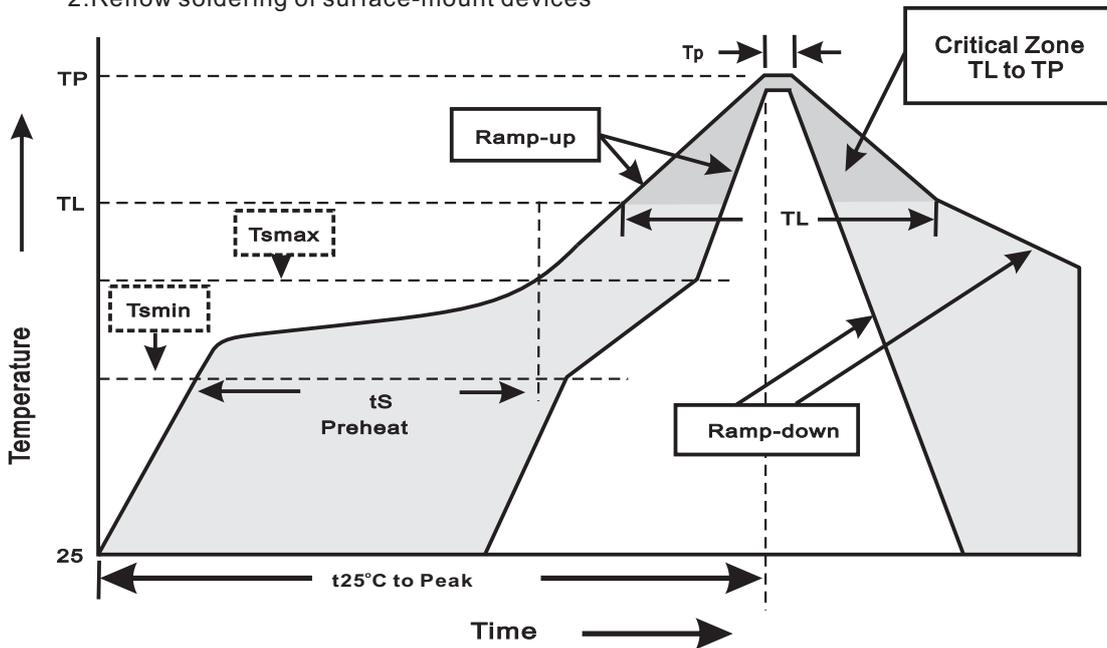
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## Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOT-323	7"	3,000	4.0	30,000	183*123*183	178	382*257*387	240,000	9.5

## Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



### 3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T <sub>L</sub> to T <sub>P</sub> )	<3°C/sec
Preheat -Temperature Min(T <sub>smmin</sub> ) -Temperature Max(T <sub>smmax</sub> ) -Time(min to max)(t <sub>s</sub> )	150°C 200°C 60~120sec
T <sub>smmax</sub> to T <sub>L</sub> -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T <sub>L</sub> ) -Time(t <sub>L</sub> )	217°C 60~260sec
Peak Temperature(T <sub>P</sub> )	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t <sub>P</sub> )	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

**MMBD4448W****High reliability test capabilities**

Item Test	Conditions	Reference
1. Solder Resistance	at 260±5°C for 10±2sec.	MIL-STD-750D METHOD-2031
2. Solderability	at 245±5°C for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R=80\%$ rate at $T_J=150^\circ\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A=25^\circ\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^\circ\text{C}$ , $I_F = I_o$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	$15P_{SIG}$ at $T_A=121^\circ\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	-55°C to +125°C dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Forward Surge	Peak Forward Surge Current	MIL-STD-750D METHOD-4066-2
9. Humidity	at $T_A=85^\circ\text{C}$ , RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
10. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031